

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"6515324"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 13:35
L2	1	"5625944".PN.	USPAT; USOCR	OR	ON	2005/10/07 13:36
L7	12	@ad<="20040409" and 'Power semiconductor' and 'snap-fit'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:53
L8	0	@ad<="20040409" and 'Power semiconductor' and 'hockey puckt'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:53
L10	100	@ad<="20040409" and 'semiconductor' and 'snap-fit' same 'connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:54
L11	42	@ad<="20040409" and 'Power semiconductor module' same 'screw'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 15:13
L12	101	@ad<="20040409" and 'Power semiconductor module' and ('screws' or 'rivet')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 15:25
L13	49	@ad<="20040409" and 'Power semiconductor module' and 'housing' and ('screws' or 'rivet')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 15:25
S1	288	@ad<="20010330" and 'reducing' same 'inductance' and 'power converter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:11
S3	14	@ad<="20010330" and 'power converter' same 'reducing' same 'wiring inductance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 07:40
S4	27	@ad<="20010330" and 'power converter' and 'reducing' same 'wiring inductance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:09

S5	2	"20040113268"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:09
S6	2359	((363/147) or (363/144) or (363/131) or (361/720) or (361/728)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 08:09
S7	166	@ad<="20010330" and S6 and 'power converter'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:51
S8	1	"6028779".PN.	USPAT; USOCR	OR	ON	2004/11/27 08:12
S9	1899	((363/55) or (363/56) or (363/132) or (363/141) or (363/144)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 08:12
S10	1	"5708579".PN.	USPAT; USOCR	OR	ON	2004/11/27 08:13
S11	1	"5621636".PN.	USPAT; USOCR	OR	ON	2004/11/27 08:13
S13	2695	((257/724) or (257/E23.173) or (257/E25.016)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 08:33
S14	2	@ad<="20010330" and 'insulating substrate' same 'inductance' and 'semiconductor switch' and 'bridge'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:37
S15	3	@ad<="20010330" and 'insulating substrate' same 'inductance' and 'semiconductor switch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:38
S16	280	@ad<="20010330" and 'insulating substrate' same 'inductance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:50
S17	45	@ad<="20010330" and 'insulating substrate' same 'connection' same 'inductance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:44

S18	6	@ad<="20010330" and 'insulating substrate' same 'reducing' same 'inductance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:48
S19	1	"5399906".PN.	USPAT; USOCR	OR	ON	2004/11/27 08:46
S20	173	@ad<="20010330" and 'insulating substrate' same 'semiconductor' same 'heat sink'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 09:39
S21	5083	((257/718) or (257/713) or (257/720) or (257/E23.084) or (257/E23.092) or (257/E23.187)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/27 08:50
S22	144	@ad<="20010330" and S13 and 'insulating substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:51
S23	104	@ad<="20010330" and S21 and 'insulating substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 08:51
S24	35	@ad<="20010330" and 'insulating substrate' same 'semiconductor' same 'current path'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:42
S25	194	@ad<="20010330" and 'insulating substrate' same 'interconnection' same 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 09:19
S26	818	@ad<="20010330" and (257/717). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 09:44
S27	374	@ad<="20010330" and 'insulating substrate' same 'semiconductor' with 'power'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 10:01
S28	1445	@ad<="20010330" and (257/723). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:45

S29	424	@ad<="20010330" and 'series' with 'connection' and 'semiconductor' with 'power' and 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 10:03
S30	210	@ad<="20010330" and 'series' with 'connected' same 'semiconductor' with 'power' and 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/27 10:09
S31	120	@ad<="20010330" and 'semiconductor power' with 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:12
S33	1	'JP 11145376'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:38
S35	2	'JP 11089247'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:40
S37	2	'JP 10253612'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:42
S40	0	'EP4869923'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:46
S41	1	'EP 0987762'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:46
S44	54	'4869923'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:47
S45	1	'04869923'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 13:49
S50	1242	@ad<="20010330" and (257/724). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/30 16:06

S51	5	@ad<="20010330" and 'reducing' same 'inductance' and 'power converter' and 'bridge' with 'connect'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:11
S53	3	@ad<="20010330" and 'semiconductor' with 'power' and 'bridge-connect'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:18
S54	4	@ad<="20010330" and 'semiconductor' and 'power' and 'bridge-connect'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:52
S56	1	"6028779".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:20
S57	1	"6024060".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:20
S58	1	"5748456".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:20
S59	1	"5172310".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:21
S60	1	"5132896".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:21
S63	106	@ad<="20010330" and 'insulating substrate' and 'bridge' with 'connect'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:22
S64	11	@ad<="20010330" and 'semiconductor switches' and 'insulating substrate' and 'bridge' with 'connected'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:31
S65	1	"6028779".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:34
S66	1	"5708579".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:34
S67	1	"5621636".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:34
S68	1	"5604674".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:34
S69	1	"5289364".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:35
S70	1	"5289364".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:38
S71	35	@ad<="20010330" and 'insulating substrate' same 'semiconductor' same 'current path'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:42

S72	1245	@ad<="20010330" and (257/724). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:45
S73	1450	@ad<="20010330" and (257/723). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:46
S74	216	@ad<="20010330" and (257/725). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:46
S75	1219	@ad<="20010330" and (257/784). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 08:47
S76	1	"6011302".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:47
S77	1	"5956231".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:47
S78	1	"5463251".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:48
S79	1	"6011302".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:51
S80	1	"5956231".PN.	USPAT; USOCR	OR	ON	2005/04/26 08:51
S82	170	@ad<="20010330" and 'power semiconductor' and 'insulating substrate' and 'current'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 09:18
S83	100	Shirakawa-Shinji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/26 09:18
S84	1	"20050093122"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 08:49
S85	1029	@ad<="20040409" and 'Power semiconductor module'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 14:18
S86	147	@ad<="20040409" and 'Power semiconductor module' and 'connecting' with 'module'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/02 09:29

S87	1	"6028779".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:16
S88	1	"5708579".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:17
S89	1	"5621636".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:17
S90	48	@ad<="20040409" and 'Power semiconductor module' and 'plate' and 'housing' and 'terminal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 16:07
S91	152	@ad<="20040409" and 'semiconductor module' and 'plate' and 'housing' and 'terminal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 14:20
S92	3	@ad<="20040409" and 'semiconductor module' and 'plate' and 'housing' and 'terminal' and 'insulated substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 14:31
S94	20	@ad<="20040409" and 'semiconductor module' and 'base' and 'housing' and 'terminal' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 14:40
S95	1	"5747876".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:36
S96	24	@ad<="20040409" and 'semiconductor module' and 'base' and 'housing' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 14:45
S97	117	@ad<="20040409" and 'power semiconductor module' and 'base' and 'housing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:32
S98	1	"6313598".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:49
S99	1	"5705853".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:50
S100	1	"5579217".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:50
S101	1	"4748495".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:51
S102	1	"6519156".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:56
S103	1	"6344973".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:58
S104	1	"6053049".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:58
S105	1	"5761039".PN.	USPAT; USOCR	OR	ON	2005/10/06 14:58

S10 6	515	'SEMIKRON'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:36
S10 7	140	'SEMIKRON' and 'module'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:48
S10 9	0	'ep 0828341'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:48
S11 0	2	'ep 828341'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:50
S11 1	1	'ep 263045'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:51
S11 2	2	'ep 1263045'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:52
S11 3	3	"2002027283"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:54
S11 4	0	"2002/027283"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:53
S11 5	2	"20020027283"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:55
S11 6	3	"2002015352"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:55
S11 7	2	"2002153532"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:56

S11 8	2	"20020153532"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 15:57
S11 9	2	("4600968").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/06 15:57
S12 0	61	@ad<="20040409" and 'Power semiconductor' near ('module' or 'modular') and 'plate' and 'housing' and 'terminal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/06 16:14
S12 1	1148	@ad<="20040409" and 'Power semiconductor' near ('module' or 'modular')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:08
S12 3	10	@ad<="20040409" and 'Power semiconductor' near ('module' or 'modular') and 'snap'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:34
S12 4	48	@ad<="20040409" and ('module' or 'modular') same 'snap-on' with 'connection'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:10
S12 5	30	@ad<="20040409" and 'power' near ('module' or 'modular') and 'snap' with 'detent'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:15
S12 6	296	@ad<="20040409" and 'snap' with 'detent' and 'detent' with 'lug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:16
S12 7	14	@ad<="20040409" and 'packaging' and 'snap' with 'detent' and 'detent' with 'lug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:18
S12 8	5	@ad<="20040409" and 'connection' near 'snap' with 'detent' and 'detent' with 'lug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:21
S12 9	210	@ad<="20040409" and ('interlocking' or 'connection') and 'snap' with 'detent' and 'detent' with 'lug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:34

S13 0	296	@ad<="20040409" and 'snap' with 'detent' and 'detent' with 'lug'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:36
S13 1	1	S130 and 'Power semiconductor' near ('module' or 'modular')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:35
S13 2	1	S130 and 'Power' near ('module' or 'modular')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:35
S13 3	38	S130 and ('module' or 'modular')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:35
S13 4	399	@ad<="20040409" and 'snap' and 'detent' and 'lug' and ('module' or 'modular')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:47
S13 5	4	@ad<="20040409" and 'snap' and 'detent' and 'lug' and 'semiconductor' same ('module' or 'modular')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:37
S13 6	204	@ad<="20040409" and 'snap' and 'detent' and 'lug' and ('module' or 'modular') and 'power'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:47
S13 7	424	@ad<="20040409" and 'detent' and 'lug' and ('module' or 'modular') and 'power'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:47
S13 8	15	@ad<="20040409" and 'detent' and 'lug' and ('module' or 'modular') and 'power' same 'semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:54
S13 9	2	("5485350").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 09:58
S14 0	0	'JP "2000" 156575'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:02

S14 1	0	'JP 156575'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 09:59
S14 2	0	'JP 00156575'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:00
S14 3	37	@ad="20001013" and 'denso'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:00
S14 4	2	'JP 2000156575'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 10:02
S14 5	1060	@ad<="20040409" and 'Power semiconductor module'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 15:13
S14 6	1	"6344973".PN.	USPAT; USOCR	OR	ON	2005/10/07 10:18
S14 7	1	"6053049".PN.	USPAT; USOCR	OR	ON	2005/10/07 10:19
S14 8	2	@ad<="20040409" and 'Power semiconductor module' and 'snap' with 'fit'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 14:46
S14 9	0	@ad<="20040409" and 'modular Power semiconductor' and 'snap' with 'fit'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 11:26
S15 0	8	@ad<="20040409" and 'modular Power semiconductor'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/07 11:26
S15 1	2	("6690087").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/07 13:35
S15 2	1	"6309737".PN.	USPAT; USOCR	OR	ON	2005/10/07 11:45
S15 3	1	"6261703".PN.	USPAT; USOCR	OR	ON	2005/10/07 11:45
S15 4	1	"6066219".PN.	USPAT; USOCR	OR	ON	2005/10/07 11:46